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(54) **DETECTION FILM AND MANUFACTURING METHOD THEREFOR, DETECTION METHOD AND DEVICE FOR CHIP BONDING, AND CLASSIFICATION METHOD**

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(57) **ABSTRACT**

The disclosure relates to a detection film and a manufacturing method therefor, a detection method and device for chip bonding, and a classification method. A detection film (2) covers a chip bonded to a circuit board (11), the detection film (2) is internally provided with colloidal crystal microspheres (22) arranged in order, and based on a Bragg reflection effect of the colloidal crystal microspheres, whether each chip is tilted is determined according to light reflected by the colloidal crystal microspheres (22) on the chip.

